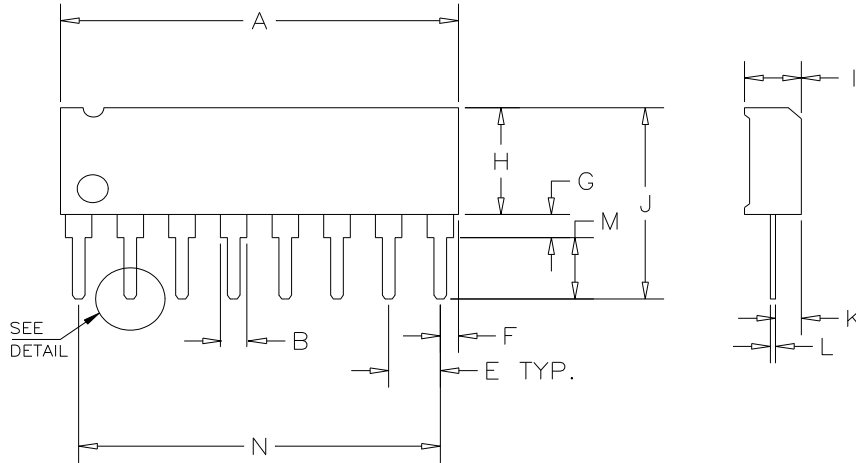


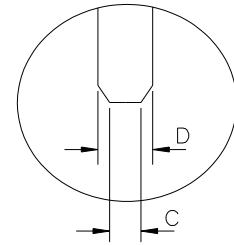
225 MIL SIP
SINGLE INLINE PACKAGE(SIP)

PACKAGE INFORMATION



NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. PACKAGE FINISH 24 TO 27 CHARMILLES GAGE.
4. ALLOWABLE MOLD FLASH IS 6 MILS PER SIDE.
5. DIMENSIONS ARE GIVEN IN INCHES.



DETAIL

JEDEC #	-	
TYPE	08 LEAD	
SYMBOL	Min	Max
A	0.760	0.762
B	0.047	0.051
C	0.023	0.027
D	0.032	0.036
E	0.100 BSC	
F	0.026	0.034
G	0.047	0.053
H	0.224	0.226
I	0.109	0.111
J	0.408	0.413
K	0.049	0.051
L	0.009	0.0115
M	0.129	0.139
N	0.700 BSC	

PREPARED BY	NK	REF. NO. DIM-SIP-01	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	NJC		0	
APPROVED BY	RM		DATE 23.11.00	

